



PK520 (v1.1) December 27, 2011

100% Material Declaration Data Sheet for Spartan®-3/-3E/-3A FT256 (Cu Wire)

Average Weight: 0.7690g

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silicon Die					0.020003	2.601
	Silicon (Si)	7440-21-3	100.00		0.020003	
Die Attach					0.006372	0.829
	Silver (Ag)	7440-22-4	77.50		0.004938	
	Bismaleimide monomer	Trade Secret	15.00		0.000956	
	Acrylate Monomer	Trade Secret	7.50		0.000478	
Mold Compound					0.382614	49.755
	Epoxy Resin	Trade Secret	5.00		0.019131	
	Phenol Resin	Trade Secret	3.00		0.011478	
	Phenol Novolac	9003-35-4	3.00		0.011478	
	Metal Hydroxide	Trade Secret	3.00		0.011478	
	Carbon Black	1333-86-4	0.30		0.001148	
	Silica Fused	60676-86-0	70.40		0.269360	
	Silica Fused	7631-86-9	15.00		0.057392	
	Silica, crystalline	14808-60-7	0.30		0.001148	
Solder Balls					0.140093	18.218
	Tin (Sn)	7440-31-5	63.00		0.088259	
	Lead (Pb)	7439-92-1	37.00		0.051834	
Copper Wire					0.009626	1.252
	Copper (Cu)	7440-50-8	98.75		0.009505	
	Palladium	7440-50-3	1.25		0.000120	

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Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Substrate					0.210292	27.346
	Copper (Cu)	7440-50-8	17.68		0.037190	
	Nickel (Ni)	7440-02-0	4.23		0.008889	
	Gold (Au)	7440-57-5	0.50		0.001061	
	Glass Fiber	65997-17-3	16.27		0.034204	
	Non Halogen Fire Retardant	1675-54-3	0.01		0.000021	
	BT (Core)	105391-33-1, 25722-66-1, 9003-36-5, 21645-51-2, 7440-50-8	46.23		0.097224	
	Solder Mask	13676-54-5, 25722-66-1, 147-14-8, 7727-43-7, 61790-53-2, 14807-96-6, 461-58-5 7723-14-0	15.08		0.031702	

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
09/16/11	1.0	Initial Xilinx release.
12/27/11	1.1	Removal of Arsenic compound.

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